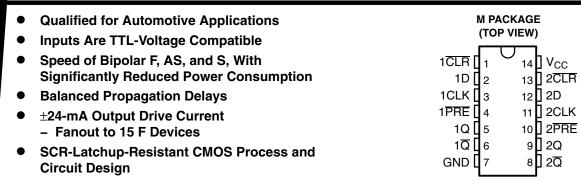
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### description/ordering information

The CD74ACT74 dual positive-edge-triggered device is a D-type flip-flop.

A low level at the preset (PRE) or clear (CLR) inputs sets or resets the outputs, regardless of the levels of the other inputs. When PRE and CLR are inactive (high), data at the data (D) input meeting the setup time requirements is transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not related directly to the rise time of the clock pulse. Following the hold-time interval, data at the D input can be changed without affecting the levels at the outputs.

#### ORDERING INFORMATION<sup>†</sup>

T <sub>A</sub>	PACKA	GE‡	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	SOIC - M	Tape and reel	CD74ACT74QM96Q1	ACT74Q

<sup>&</sup>lt;sup>†</sup> For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

## FUNCTION TABLE (each flip-flop)

	INP	OUTI	PUTS		
PRE	CLR	CLK	D	Q	Q
L	Н	Х	Х	Н	L
Н	L	X	Χ	L	Н
L	L	X	Χ	H§	Н§
Н	Н	$\uparrow$	Н	Н	L
Н	Н	$\uparrow$	L	L	Н
Н	Н	L	Χ	$Q_0$	$\overline{Q}_0$

<sup>§</sup> This configuration is nonstable; that is, it does not persist when PRE or CLR returns to its inactive (high) level.



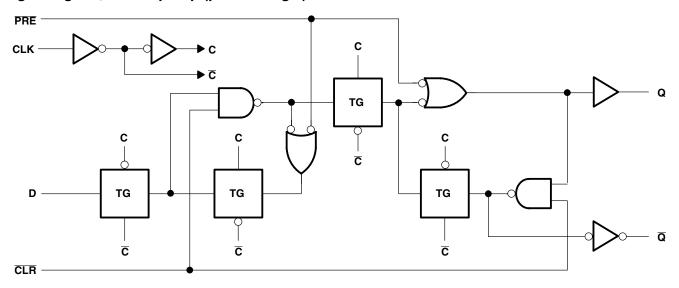
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



<sup>&</sup>lt;sup>‡</sup> Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

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### logic diagram, each flip-flop (positive logic)



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub>	0.5 V to 6 V
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0 or V <sub>I</sub> > V <sub>CC</sub> ) (see Note 1)	±20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> ) (see Note 1)	±50 mA
Continuous output current, I <sub>O</sub> (V <sub>O</sub> = 0 to V <sub>CC</sub> )	±50 mA
Continuous current through V <sub>CC</sub> or GND	±100 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2)	86°C/W
Storage temperature range, T <sub>stq</sub>	$-65^{\circ}$ C to $150^{\circ}$ C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. The package thermal impedance is calculated in accordance with JESD 51-7.

### recommended operating conditions (see Note 3)

		T <sub>A</sub> = 25°C		–40°0 125	UNIT	
		MIN	MAX	MIN	MAX	
V <sub>CC</sub>	Supply voltage	4.5	5.5	4.5	5.5	V
V <sub>IH</sub>	High-level input voltage	2		2		V
V <sub>IL</sub>	Low-level input voltage		8.0		0.8	V
VI	Input voltage	0	$V_{CC}$	0	$V_{CC}$	V
Vo	Output voltage	0	$V_{CC}$	0	$V_{CC}$	V
I <sub>OH</sub>	High-level output current		-24		-24	mA
I <sub>OL</sub>	Low-level output current		24		24	mA
Δt/Δν	Input transition rise or fall rate		10		10	ns/V

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS			T <sub>A</sub> = 25°C		–40°C to 125°C		UNIT
		V <sub>CC</sub>	MIN	MAX	MIN	MAX		
		$I_{OH} = -50 \mu A$	4.5 V	4.4		4.4		
V <sub>OH</sub>		$I_{OH} = -24 \text{ mA}$	4.5 V	3.94		3.7		٧
		$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V			3.85		
	$V_{I} = V_{IH}$ or $V_{IL}$	$I_{OL} = 50 \mu A$	4.5 V		0.1		0.1	V
V <sub>OL</sub>		I <sub>OL</sub> = 24 mA	4.5 V		0.36		0.5	
		$I_{OL} = 50 \text{ mA}^{\dagger}$	5.5 V				1.65	
l <sub>l</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND		5.5 V		±0.1		±1	μΑ
Icc	$V_I = V_{CC}$ or GND,	I <sub>O</sub> = 0	5.5 V		4		80	μΑ
$\Delta$ l $_{CC}$ $^{\ddagger}$	V <sub>I</sub> = V <sub>CC</sub> - 2.1 V		4.5 V to 5.5 V		2.4		3	mA
C <sub>i</sub>					10		10	pF

<sup>†</sup> Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 75-Ω transmission-line drive capability at 125°C.

### **ACT INPUT LOAD TABLE**

INPUT	UNIT LOAD
Data	0.53
PRE or CLR	0.58
CLK	1

Unit load is  $\Delta I_{CC}$  limit specified in electrical characteristics table (e.g., 2.4 mA at 25°C).

# timing requirements over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

			–40°C to 125°C		UNIT
			MIN	MAX	
f <sub>clock</sub>	Clock frequency			85	MHz
	Dula a douation	PRE or CLR low	5		
t <sub>w</sub>	Pulse duration	CLK	5.7		ns
t <sub>su</sub>	Setup time	Data	4		ns
t <sub>h</sub>	Hold time	Data after CLK↑	0		ns
t <sub>rec</sub>	Recovery time, before CLK↑	CLR↑ or PRE↑	2.7		ns

<sup>‡</sup> Additional quiescent supply current per input pin, TTL inputs high, 1 unit load

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# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO	–40°0 125	UNIT	
	(INPUT)	(OUTPUT)	MIN	MAX	
f <sub>max</sub>			85		MHz
t <sub>PLH</sub>	014	O	2.4	9.5	
t <sub>PHL</sub>	CLK	Q or Q	2.4	9.5	ns
t <sub>PLH</sub>	PRE or CLR	Q or Q	2.9	11.5	ns
t <sub>PHL</sub>	PRE UI CEN	Q 01 Q	3.1	12.5	115

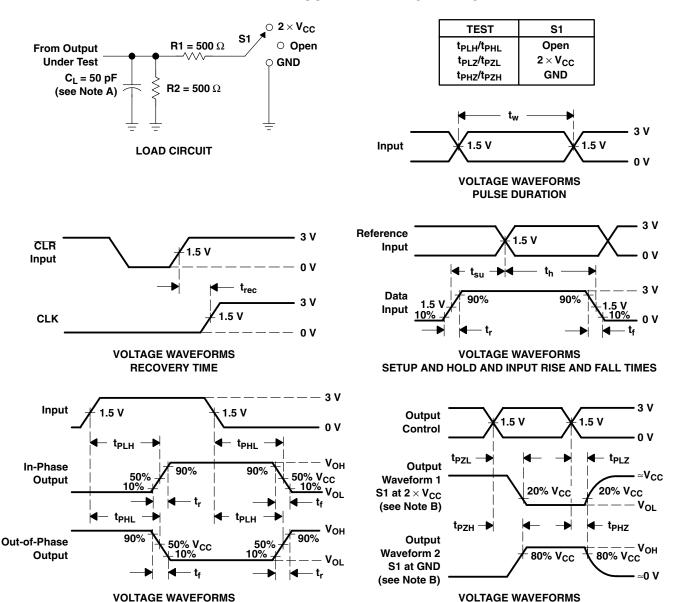
## operating characteristics, $V_{CC}$ = 5 V, $T_A$ = 25°C

	PARAMETER	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	55	pF



**OUTPUT ENABLE AND DISABLE TIMES** 

### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and test-fixture capacitance.

PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_r = 3 \text{ ns}$ ,  $t_f = 3 \text{ ns}$ . Phase relationships between waveforms are arbitrary.
- D. For clock inputs,  $f_{max}$  is measured with the input duty cycle at 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd</sub>.
- G. t<sub>PZI</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
- H. t<sub>PLZ</sub> and t<sub>PHZ</sub> are the same as t<sub>dis</sub>.

Figure 1. Load Circuit and Voltage Waveforms



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#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	<b>RoHS</b> (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
CD74ACT74QM96G4Q1	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	ACT74Q
CD74ACT74QM96G4Q1.A	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	ACT74Q

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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#### OTHER QUALIFIED VERSIONS OF CD74ACT74-Q1:

Catalog: CD74ACT74

<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

### PACKAGE OPTION ADDENDUM

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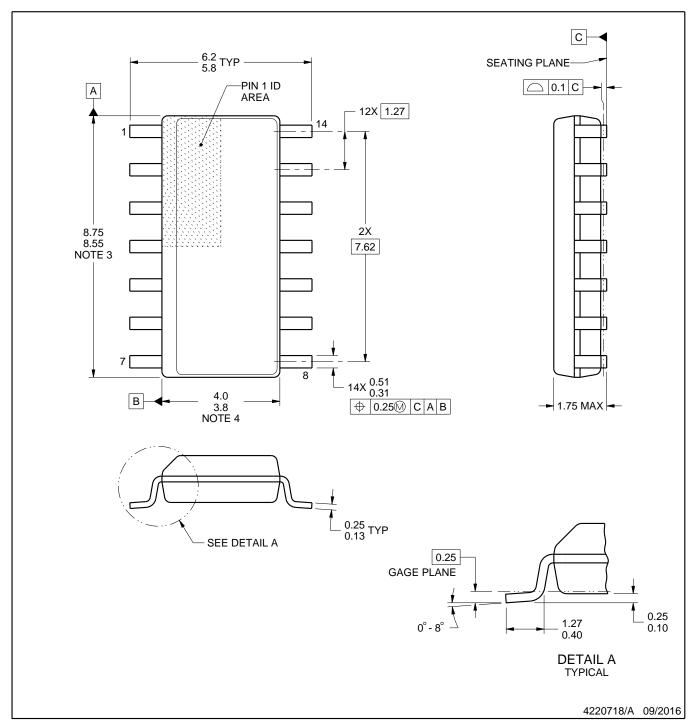
Military : CD54ACT74

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications



SMALL OUTLINE INTEGRATED CIRCUIT



### NOTES:

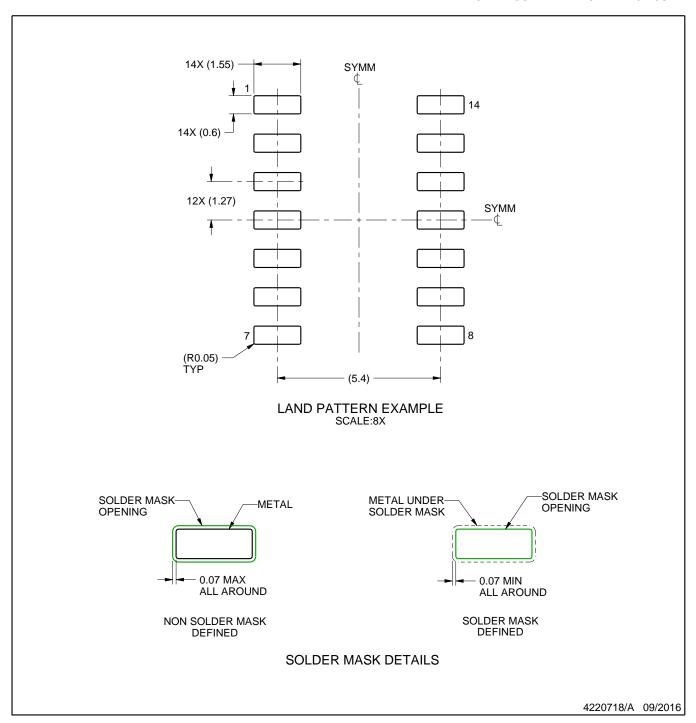
- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.



SMALL OUTLINE INTEGRATED CIRCUIT



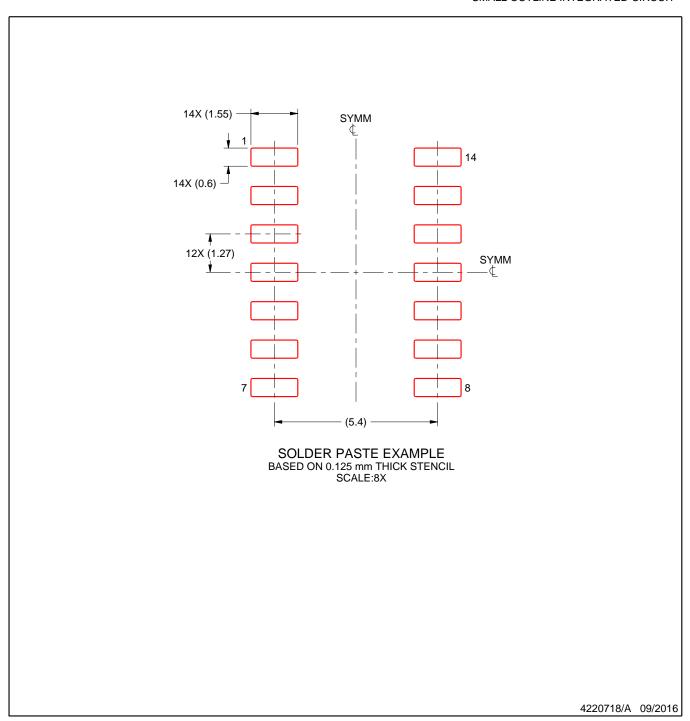
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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